AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 09/963389

Filing Date: September 27, 2001

Title: Method and Apparatus for In-Circuit Testing of Sockets

Assignee: Intel Corporation

Page 2 Dkt: 884.996US1 (INTEL)

## **IN THE SPECIFICATION**

Please amend the specification as follows.

Please replace paragraph 16 with the following paragraph.

[0016] Fig. 1 shows a block diagram of a system for in-circuit socket testing according to an example embodiment of the present invention. The system includes a socket 12 that is electrically connected to a motherboard or printed circuit board 16 via ball grid array or other type pins 14. Generally, the pins 14 of socket 12 are soldered onto printed circuit board 16. A test module 10 attaches to all pins of socket 12. A test fixture 18 may be connected to every node or trace on the printed circuit board 16 via test points 20. Further, test fixture 18 may be a "bed of nails" fixture where printed circuit board 16 lies on top of a portion of test fixture 18 to make the electrical connections. Test fixture 18 may be any type of high-end tester or low-end tester, for example, HP3070, GENRAD machines, etc. Test fixture 18 may include a power supply 22 that provides power and ground signals to socket 12 through printed circuit board 16, or power and ground may be supplied external to test fixture 18. Test fixture 18 may be used to control the testing and monitor the resuts results.